	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	2538348	(underfill or fill$6 or inject$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:03
2	BRS	L2	1904720	wafer$3 or substrate$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:04
3	BRS	L3	19864	"flip chip"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:04
4	BRS	L4	3665905	dic$6 or separat$6 or singulat$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:05
5	BRS	L5	894488	gap$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:05

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	1869012	chip$3 or die$3 or dice or packag$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:06
7	BRS	L7	77011	1 near8 5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:06
8	BRS	L8	186	7 same 2 same 4 same 6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:08
9	BRS	L9	92	8 and 3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:09

Handwritten annotations:

L6 → L20 chips! or die or dies or packages   plural
                                                1 st dicing
bond   of wafer
encaph   chips - - -
              substrates - - -
      → dicing - - -
              encapsulating / resin - - -
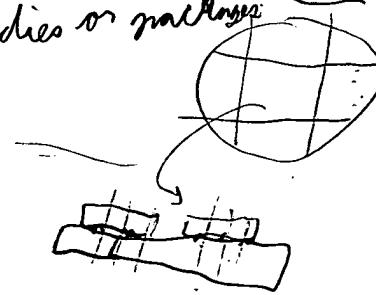
multiple or many or numbers or several

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	112142	(substrate or substrates or wafer or wafers) near8 (chip or chips or die or dies or dice or packages)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 13:11
2	BRS	L2	3608787	(multiple or many or several or multichip$3 or multi-chip$3 or (multi adj chip$3)) *mcm*	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 13:12
3	BRS	L3	1839871	encapsulat$4 or fill$4 or underfill$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 13:13
4	BRS	L4	3580550	dic$4 or singulat$4 or separat$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 10:21
5	BRS	L5	533	1 same 2 same 3 same 4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 10:21

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	1092105	chip or chips or die or dies or dice or packages	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 13:11
7	BRS	L7	1909013	(substrates or substrate or wafer or wafers)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 13:11
8	BRS	L8	3516216	dicing or singulat$6 or separat$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 13:12
9	BRS	L9	10555	2 near8 6 near8 7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 13:13
10	BRS	L10	1810	9 same 8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 13:13

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L11	147	10 same 3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 13:13